

1

2

3

4

A

A

B

B

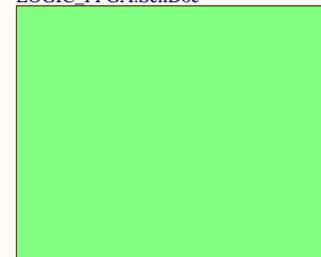
C

C

D

D

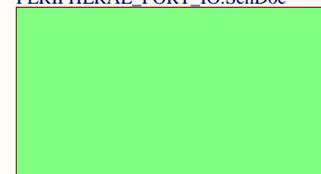
U_LOGIC_FPGA
LOGIC_FPGA.SchDoc



U_DIGITAL_IO
DIGITAL_IO.SchDoc



U_PERIPHERAL_PORT_IO
PERIPHERAL_PORT_IO.SchDoc



U_RAM
RAM.SchDoc



U_POWER_SUPPLY
POWER_SUPPLY.SchDoc



U_FPGA_POWER_AND_CONFIGURATION
FPGA_POWER_AND_CONFIGURATION.SchDoc



SCRW1



SCRW - 4-40x1/4-Nylon



SCRW - 4-40x1/4-Nylon



SCRW - 4-40x1/4-Nylon



SCRW - 4-40x1/4-Nylon



SCRW - 4-40x1/4-Nylon

STDOFF1



STDOFF - 4-40-5/8"

STDOFF2



STDOFF - 4-40-5/8"

M1

Rubber Bumper

Rubber Bumper Standoff

Title	LOGi-Pi Top Level		
Revision:	R1.5	Sheet	1 of 7
Date:	3/20/2017	Engineer:	Michael Jones



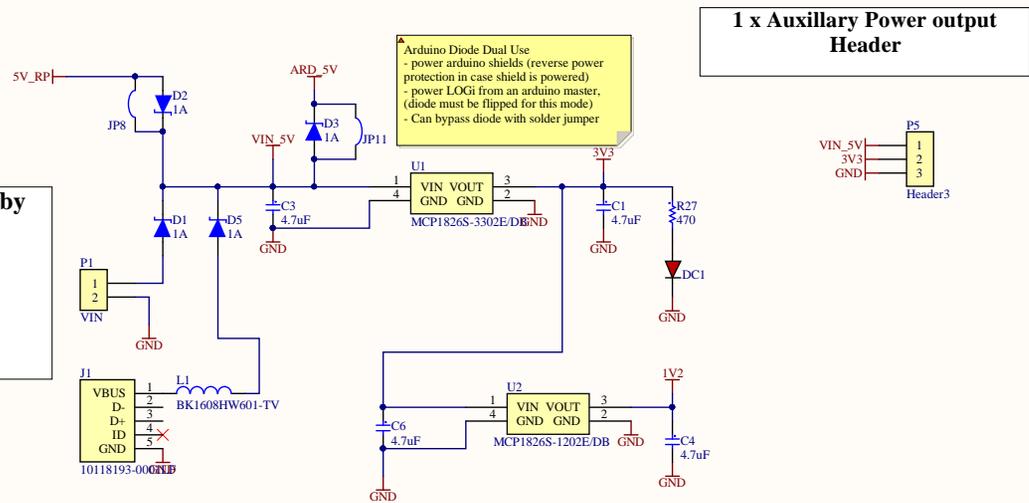
1

2

3

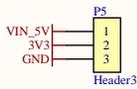
4

**Power: By Default Power will be supplied by the .
Raspberry Pi
Optionally power can be supplied through
FPGA VIN header.**



Arduino Diode Dual Use
 - power arduino shields (reverse power protection in case shield is powered)
 - power LOGi from an arduino master. (diode must be flipped for this mode)
 - Can bypass diode with solder jumper

1 x Auxillary Power output Header



- LOGI-LOGO
- LOGO1
- VALENTFX-LOGO-500
- Logo2
- VALENTFX-LOGO-750
- Logo3

Title	Power Supply	
Revision:	R1.5	Sheet 2 of 7
Date:	3/20/2017	Engineer: Michael Jones



A

B

C

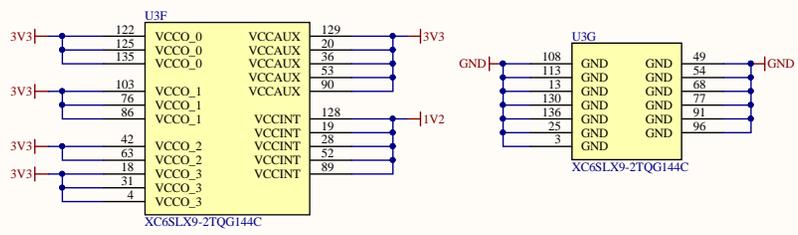
D

A

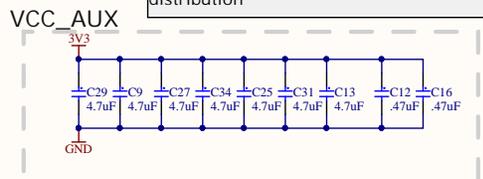
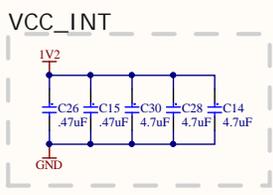
B

C

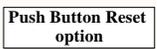
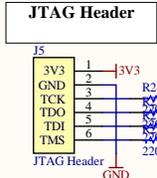
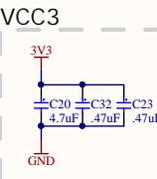
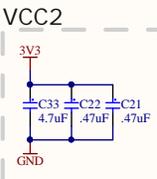
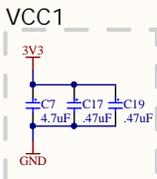
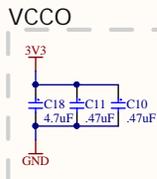
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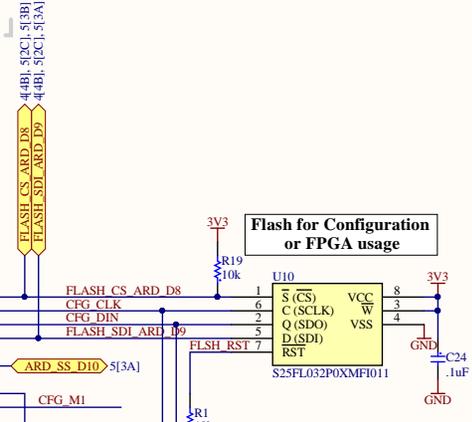
GPIO Expander - Handling of General Config/Control Pins



Decoupling cap configuration recommended by Xilinx UG393 (V1.2) for Spartan 6 power distribution



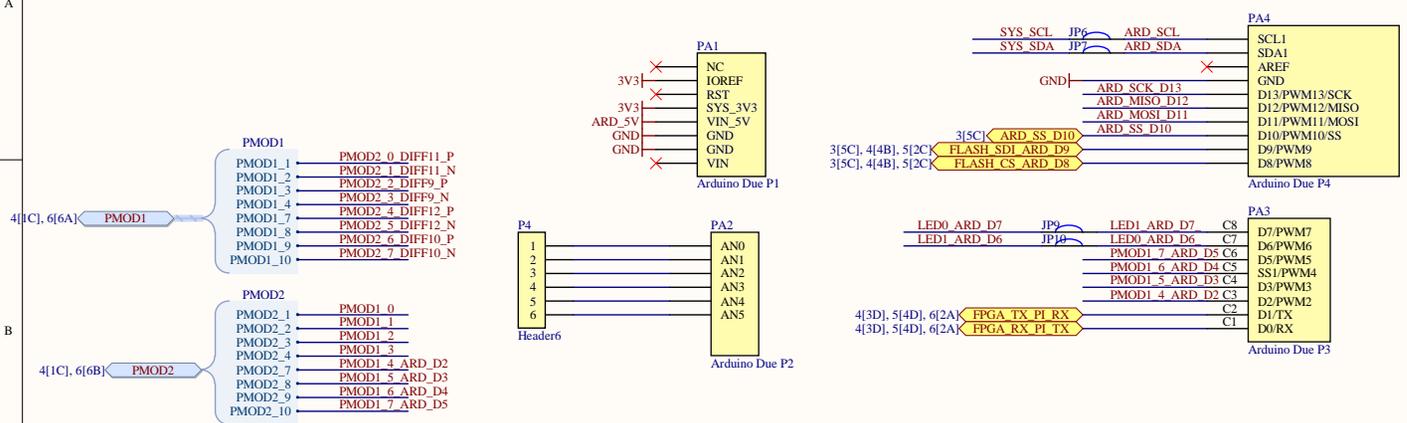
Flash for Configuration or FPGA usage



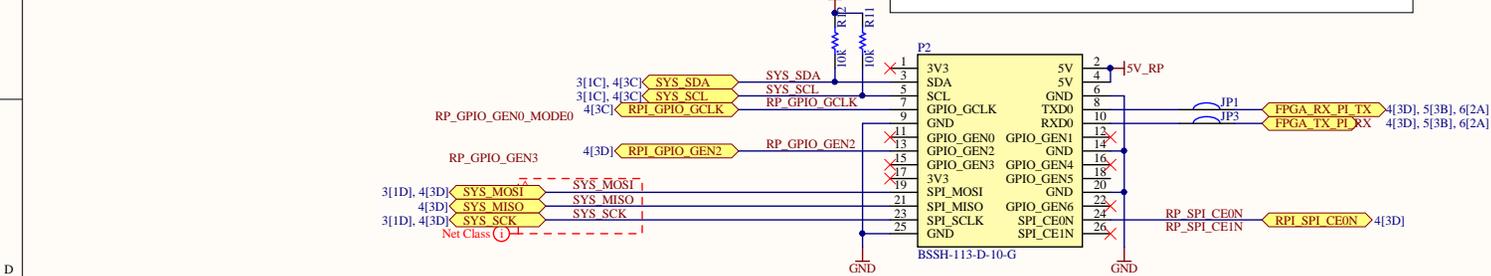
[M[1:0] pull ups are set to select SelfConfig by default. See UG380 p40 for pin descriptions.
01 = SelfConfig
11 = SlaveConfig

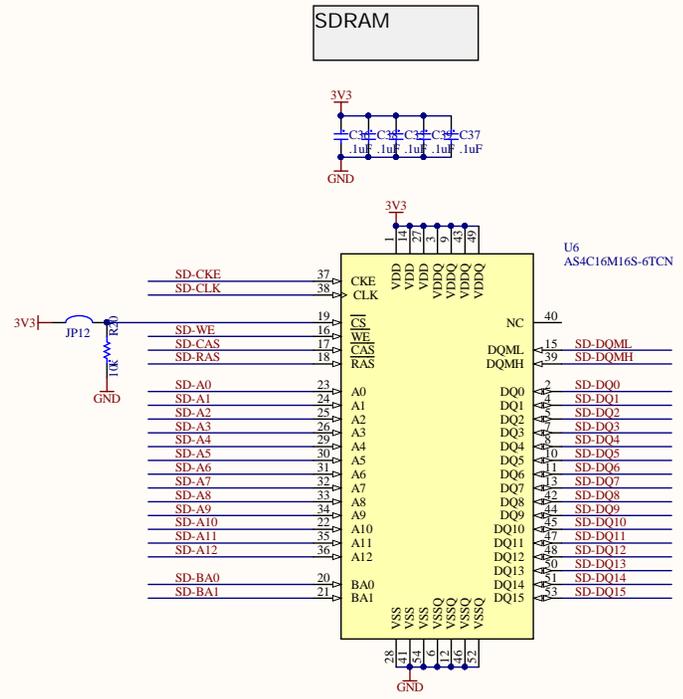
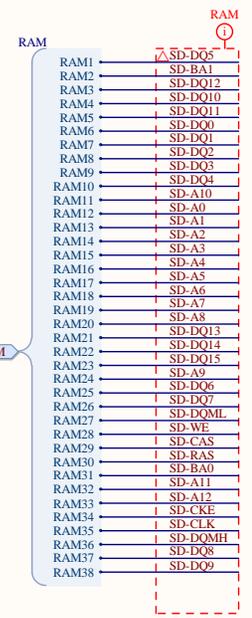
Hard wire Mode pin 0. Mode1 controlled from GPIO EXP. default (0) self config for standalone mode. User can solder jumper to hard wire to self config

Arduino IO



Raspberry Pi IO - SPI, I2C, UART, 3XGPIO to FPGA





PCB Fabrication Notes

Unless otherwise specified, all dimensions are in inches
 Overall Dimension: 3.471" x 3.485"
 Finished Thickness: .062"
 Layer Count: 4
 Min Thru Hole: 13 mil
 Annular Ring: 7 mil
 Min Trace/Space: 6 mil
 Drill Count: 569
 Pad Count: 378
 Component Count: 116
 Via Count: 423

Plating: Gold ENIG
 Solder Mask: Black
 Legend: White Non-Conductive Ink SPI Process
 RSZ: 2X Center Format, 2X Leading Zero Suppression
 Escalator: 20 Mil Format, 20 Trailing Zero Suppression

Layer Details: 4-Layer Stackup POLARITY

01 - Top Copper	POSITIVE
02 - Inner Copper (Ground)	POSITIVE
03 - Inner Copper (VDD)	POSITIVE
04 - Bottom Copper	POSITIVE
05 - Top Soldermask	
06 - Bottom Soldermask	
07 - Top Solder Paste	
08 - Bottom Solder Paste	
09 - Top Solder Mask	
10 - Bottom Solder Mask	
11 - Board Outline	
12 - 20 Mil Drill - System	
13 - Board Dimensions	
14 - Single Board Fabrication Notes	
15 - Single Board Score/Tab Route	
16 - 20 Body	
17 - Assembly Outline - Top	
18 - Panel Dimensions	
19 - Panel Score/Tab Route	
20 - Panel Dimensions	

.TXT/.DRL - NC-D

